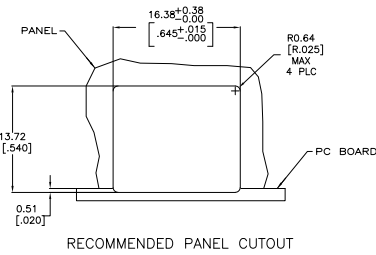
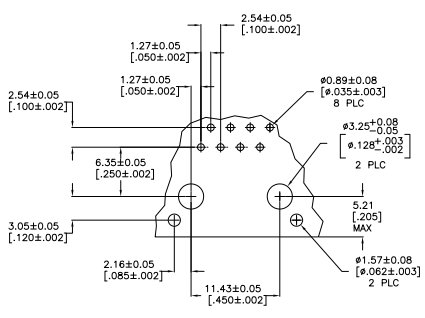
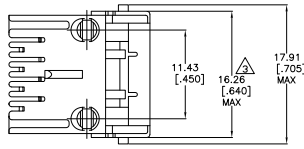
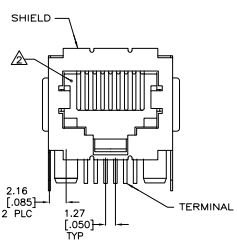
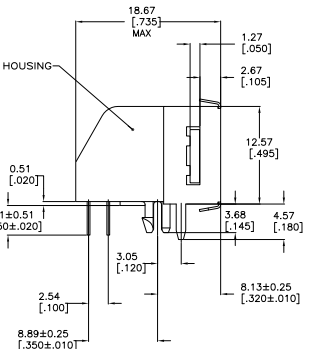


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REV	DATE	DESCRIPTION	BY	CHK	APP
AA	00				
B		ECO-07-000206			



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)

RECOMMENDED PANEL CUTOUT

1. MATERIAL:  
 HOUSING (SEE TABLE) - COLOR: BLACK  
 TERMINAL - 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27μm [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81μm [.000150] THICK MATTE TIN IN SOLDER AREA OVER 1.27μm [.000050] THICK NICKEL UNDERPLATE  
 SHIELD - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 3.0μm [.000120] MINIMUM THICK REFLOWED TIN

△ CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.

△ DIMENSIONS MEASURED ALONG FRONT EDGES OF MATING FACE

YES	HIGH TEMP NYLON	5555141-3
NO	PBT POLYESTER	5555141-1
IR PROCESS COMPATIBLE	HOUSING MATERIAL	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		G. CASSETTA, MANAGER		Toto Electronics Corporation	
DRAWN BY: J. WESTMAN		CHECKED BY: J. WESTMAN		Harrisburg, PA 17105-3608	
DATE: 108-1163	REVISED BY: J. WESTMAN	DATE: 114-2048	REVISED BY: J. WESTMAN	USE: MODULAR JACK ASSEMBLY, SHIELDED, B POSITION, LOW PROFILE, RIGHT ANGLE, PANEL GROUND WITH PANEL STOPS	REWORKED TO: ---
SEE NOTE 1	SEE NOTE 1	SEE NOTE 1	SEE NOTE 1	SEE NOTE 1	SEE NOTE 1
CUSTOMER DRAWING		A100779		Q=5555141	